



RoHS Compliant

| REV | MODIFICATION | DATE | DRAW |
|-----|------------------------|------------|----------|
| A3 | Release To ECN20120607 | 2012.06.26 | Michelle |
| A4 | Release To ECN20140102 | 2014.01.13 | Michelle |
| A5 | Release To ECN20150603 | 2015.06.09 | Michelle |

Specification
 1.Current Rating:3A AC/DC
 2.Voltage Rating:250V AC/DC
 3.Contact Resistance:20mΩ Max.
 4.Insulation Resistance:1000MΩ Min. At DC 500V
 5.Dielectric Withstanding Voltage:AC1000V/Minute
 6.Operating Temperature:-25°C~+85°C

Material:
 1.Housing:High Temperature Thermoplastic UL94V-0
 2.Contact Pin:Copper Alloy SQ. Pin 0.64mm

Finish:
 1.Housing:See P/N Option
 2.Contact Pin:See P/N Option

Part No.: AD03615 XX X X 5 A

No. Of Pin: 02~20
 Packing: 5:Bag

Housing Material
 0:PA66 UL94V-0 Red
 T:PA66 UL94V-0 White

Plating
 1:Bright Tin Plated Over Cu
 3:Gold Plated Over Nickel
 A:Bright Tin Plated Over Nickel

| PIN | DIM.A | DIM.B | PIN | DIM.A | DIM.B | PIN | DIM.A | DIM.B | PIN | DIM.A | DIM.B |
|-----|-------|-------|-----|-------|-------|-----|-------|-------|-----|-------|-------|
| 02 | 2.54 | 5.10 | 07 | 15.24 | 17.88 | 12 | 27.94 | 30.64 | 17 | 40.64 | 43.40 |
| 03 | 5.08 | 7.68 | 08 | 17.78 | 20.44 | 13 | 30.48 | 33.20 | 18 | 43.18 | 45.94 |
| 04 | 7.62 | 10.24 | 09 | 20.32 | 23.00 | 14 | 33.02 | 35.74 | 19 | 45.72 | 48.50 |
| 05 | 10.16 | 12.78 | 10 | 22.86 | 25.54 | 15 | 35.56 | 38.30 | 20 | 48.26 | 51.05 |
| 06 | 12.70 | 15.24 | 11 | 25.40 | 28.10 | 16 | 38.10 | 40.84 | | | |

發行
 104.6.09
 文管中心

金上達科技股份有限公司
GOLDENSUNDA TECHNOLOGY CO.,LTD

TOLERANCE UNLESS OTHERWISE SPECIFIED
 .x± 0.35 x.'± 2'
 .xx± 0.25 .x'± 1'
 .xxx± 0.15 .xx'± 0.5'

PROJ.

APR. C.F.Liao 20150609
 CHK. Abel 20150609
 DRA. Michelle 20150609

TITLE: Wire To Board Wafer 2.54mm 90° DIP Short Back Board

PART NO. AD03615XXXX5A
 DWG NO. AD03615XXXX5A

UNITS: mm
 SIZE: A4
 SCALE 4:1
 SHEET 1 / 1
 REV A5

CUSTOMER DRAWING